






APPLICABLE STANDARD					
	Operating Temperature Range	-55 °C to +105 °C ⁽¹⁾	Storage Temperature Range	-10 °C to +60 °C ⁽²⁾	
Rating	Voltage	100 V AC	Storage Humidity Range	Relative humidity 85 % MAX (Not dewed)	
	Current	0.5 A	Operating Humidity Range		
SPECIFICATIONS					
ITEM		TEST METHOD		REQUIREMENTS	
QT		AT			
CONSTRUCTION					
General Examination		Visually and by measuring instrument.		According to drawing.	
Marking		Confirmed visually.			
ELECTRIC CHARACTERISTICS					
Contact Resistance		100 mA(DC or 1000 Hz)		30 mΩ MAX ⁽³⁾	
Insulation Resistance		250 V DC		1000 MΩ MIN	
Voltage Proof		300 V AC for 1 min.		No flashover or breakdown. 	
MECHANICAL CHARACTERISTICS					
Insertion and Withdrawal Forces		Measured by applicable connector.		Insertion Force: 40.0 N MAX Withdrawal Force: 4.0 N MIN	
Mechanical Operation		100 times insertions and extractions.		1)Contact Resistance : 40 mΩ MAX ⁽³⁾ 2)No damage, crack and looseness of parts.	
Vibration		Frequency 10 to 55 to 10 Hz, approx 5 min. Single amplitude: 0.75 mm, 10 cycles for 3 axial directions.		1)No electrical discontinuity of 1 μs. 2)No damage, crack and looseness of parts.	
Shock		490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.			
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)		Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.		1)Contact Resistance : 40 mΩ MAX ⁽³⁾ 2)Insulation Resistance: 1000 MΩ MIN	
Rapid Change of Temperature		Temperature: -55 → +85 °C Time : 30 → 30 min. Under 5 cycles. (Relocation time to chamber: within 2 to 3 MIN)		3)No damage, crack and looseness of parts.	
Dry Heat		Exposed at +105 °C, 96 h		1)Contact Resistance : 40 mΩ MAX ⁽³⁾ 2)No damage, crack and looseness of parts.	
Cold		Exposed at -55 °C, 96 h			
Resistance to Soldering Heat		1)Reflow soldering: Peak TMP: 260 °C MAX Reflow TMP: 220 °C MIN for 60 sec 2)Soldering irons: 360 °C MAX for 5 sec.		No deformation of case of excessive looseness of the terminal.	
Solderability		Soldered at solder temperature 240 ± 3 °C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	2	DIS-F-00003292	MT. ITANO	HT. YAMAGUCHI	18. 04. 16
REMARKS			APPROVED	NH. NAKATA	17. 11. 01
(1) Include temperature rise caused by current-carrying.			CHECKED	MK. NAGATA	17. 10. 31
(2) "Storage" means a long-term storage state for the unpacked part before assembly to pcb.			DESIGNED	K.J. NISHIWAKI	17. 10. 31
(3) Contact resistance of relay board is not included. It becomes contact resistance for 1 connector. 			DRAWN	K.J. NISHIWAKI	17. 10. 31
Unless otherwise specified, refer to IEC 60512.					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-376552-00-00
	SPECIFICATION SHEET		PART NO.		FX27-60S-0. 8SV
	HIROSE ELECTRIC CO., LTD.		CODE NO.		CL577-1003-0-00  1/1